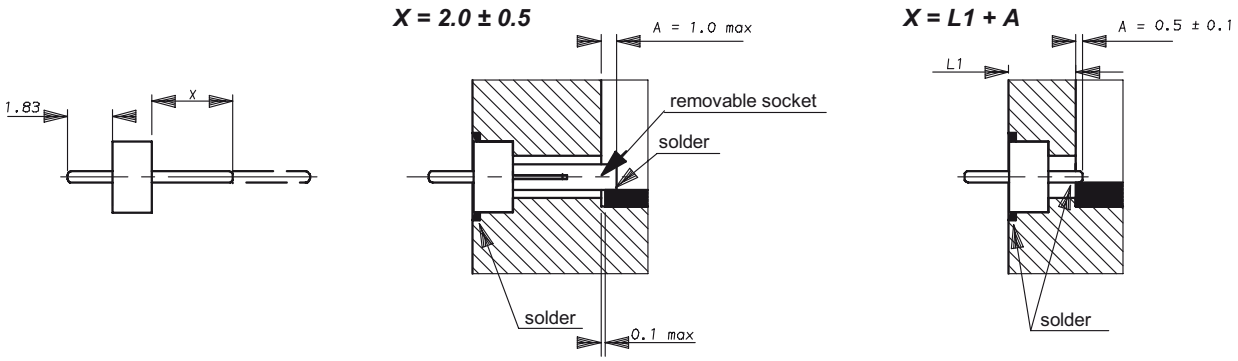
SMA

GLASS BEAD AND CONNECTOR ASSEMBLY INTO THE MICRO ELECTRONIC PACKAGE



GLASS BEAD

1. Adjust X by cutting the pin if necessary
2. Introduce the glass bead into its cavity
3. Place a ring of solder in the groove around the glass bead (a 0.3 mm wire dia. of solder is recommended)
4. Solder the pin (or optional socket) on the PCB trace inside the package

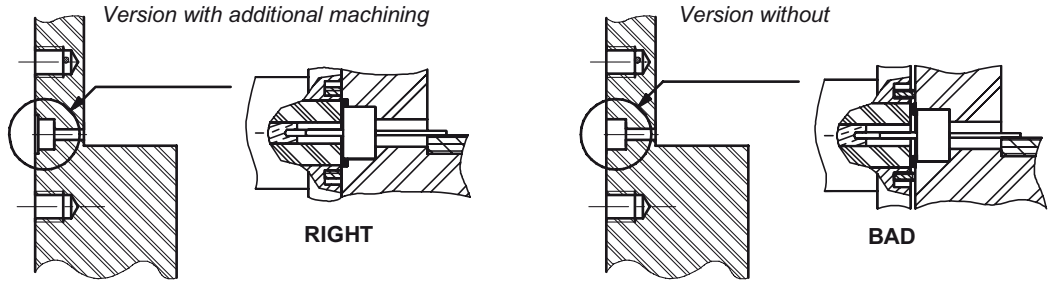
IMPORTANT

For maximum RF performance, the link track/pin must be as thin as possible. Therefore, we advise to follow the A dimension rigorously, by soldering accurately the pin or the socket directly on the trace.

CONNECTOR RECEPTACLE

Place the "EMI" screening gasket in the groove of the receptacle (if applicable). Introduce gently the receptacle on the glass bead pin, then screw the flange (use the appropriated tool for screw-in receptacle).

GLASS BEAD MOUNTING



The Radiall panel drilling on page 8-24 recommends an additional bore or chamfer machining on the outer edge of the glass bead housing. This additional machining allows to place a pre-form (solder stick Dia. 0.3 mm) before soldering.

After mounting, solder is flush and allows the right positioning of the receptacle.
The EMI gasket efficiency is guaranteed.

Notes
There is not too much welding.